What is claimed is:

1. A method of polishing a substrate, comprising:

rotating a polishing table supporting a polishing pad; and

polishing the substrate by pressing the substrate against a polishing surface of the polishing pad by a polishing head,

wherein polishing the substrate includes:

an oscillation polishing process of polishing the substrate while causing the polishing head to oscillate along the polishing surface;

a static polishing process of polishing the substrate with the oscillation of the polishing head stopped,

a finish polishing process performed after the static polishing process, the finish polishing process comprising determining a finish polishing end point by adding a preset fixed time to a polishing time at the static polishing end point or multiplying a polishing time at the static polishing end point by a preset coefficient,

the static polishing process is performed after the oscillation polishing process, and

the static polishing process comprises determining a static polishing end point which is a point in time at which a rate of change of torque for rotating the polishing table has reached a change-rate threshold value.

2. The method according to claim 1, wherein polishing the substrate comprises an oscillation stop operation which stops the oscillation of the polishing head after the torque has reached a preset torque threshold value or after a current polishing time has reached a preset oscillation polishing time.

3. The method according to claim 2, wherein the oscillation stop operation comprises stopping the oscillation of the polishing head when the polishing head is at a preset stop position above the polishing table.

4. The method according to claim 1, wherein determining the static polishing end point comprises determining a point in time at which the rate of change decreases to reach the change-rate threshold value.

5. The method according to claim 1, wherein determining the static polishing end point comprises determining a point in time at which the rate of change increases to reach the change-rate threshold value.

6. The method according to claim 1, wherein the finish polishing process comprises polishing the substrate while causing the polishing head to oscillate along the polishing surface.

7. The method according to claim 1, wherein the polishing head is on an axis of the polishing table while the polishing head is oscillating.

8. A polishing apparatus for polishing a substrate, comprising:

a polishing table for supporting a polishing pad;

a table motor configured to rotate the polishing table;

a torque measuring device configured to measure a torque for rotating the polishing table;

a polishing head configured to polish the substrate by pressing the substrate against a polishing surface of the polishing pad;

a polishing-head oscillation arm coupled to the polishing head;

an oscillation motor coupled to the polishing-head oscillation arm and configured to cause the polishing head to oscillate along the polishing surface;

an operation controller configured to control an operation of the polishing apparatus,

wherein the operation controller is configured to:

instruct the polishing apparatus to perform an oscillation polishing process of polishing the substrate while rotating the polishing table and causing the polishing head to oscillate along the polishing surface;

instruct the polishing apparatus to perform, after the oscillation polishing process, a static polishing process of polishing the substrate while rotating the polishing table with the oscillation of the polishing head stopped, and

determine a static polishing end point which is a point in time at which a rate of change of the torque for rotating the polishing table has reached a change-rate threshold value during the static polishing process;

instruct the polishing apparatus to perform a finish polishing process after the static polishing process; and determine a finish polishing end point by adding a preset fixed time to a polishing time at the static polishing end point or multiplying a polishing time at the static polishing end point by a preset coefficient.

9. The polishing apparatus according to claim 8, wherein the operation controller is configured to instruct the oscillation motor to stop the oscillation of the polishing head after the torque has reached a preset torque threshold value or after a current polishing time has reached a preset oscillation polishing time.

10. The polishing apparatus according to claim 9, wherein the operation controller is configured to instruct the oscillation motor to stop the oscillation of the polishing head when the polishing head is at a preset stop position above the polishing table.

11. The polishing apparatus according to claim 8, wherein the polishing head is on an axis of the polishing table.

12. The polishing apparatus according to claim 8, wherein the operation controller is configured to instruct the polishing apparatus to perform the finish polishing process while

causing the polishing head to oscillate along the polishing surface.